EC3SM-10.000M

Vibration





Series 4.0mm Epoxy Base SMD Crystal Frequency Tolerance/Stability ±50ppm at 25°C, ±100ppm over 0°C to +70°C

Mode of Operation -AT-Cut Fundamental

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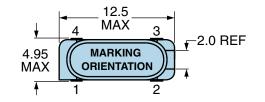
- Nominal Frequency 10.000MHz

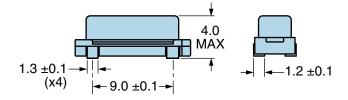
Load Capacitance 18pF Parallel Resonant

ELECTRICAL SPECIFICATIONS				
Nominal Frequency	10.000MHz			
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C			
Aging at 25°C	±5ppm/year Maximum			
Load Capacitance	18pF Parallel Resonant			
Shunt Capacitance (C0)	7pF Maximum			
Equivalent Series Resistance	70 Ohms Maximum			
Mode of Operation	AT-Cut Fundamental			
Drive Level	1mWatts Maximum			
Storage Temperature Range	-40°C to +85°C			
Insulation Resistance	500 Megaohms Minimum at 100Vdc			
ENVIRONMENTAL & MEC	HANICAL SPECIFICATIONS			
Fine Leak Test	MIL-STD-883, Method 1014 Condition A			
Gross Leak Test	MIL-STD-883, Method 1014 Condition C			
Mechanical Shock	MIL-STD-202, Method 213 Condition C			
Resistance to Soldering Heat	MIL-STD-202, Method 210			
Resistance to Solvents	MIL-STD-202, Method 215			
Solderability	MIL-STD-883, Method 2003			
Temperature Cycling	MIL-STD-883, Method 1010			

MECHANICAL DIMENSIONS (all dimensions in millimeters)

MIL-STD-883, Method 2007 Condition A





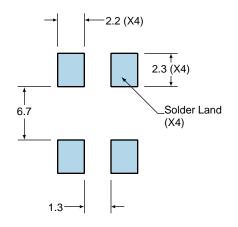
PIN	CONNECTION
1	Crystal
2	Connected to Pin 3
3	Connected to Pin 2
4	Crystal
LINE	MARKING
1	E10.000 E=Ecliptek Designator

EC3SM-10.000M



Suggested Solder Pad Layout

All Dimensions in Millimeters

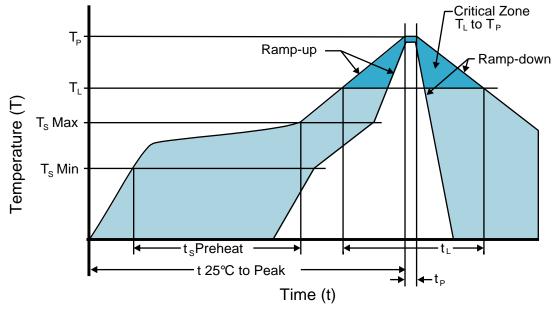


All Tolerances are ±0.1

ECLIPTEK CORPORATION

Recommended Solder Reflow Methods

EC3SM-10.000M



Low Temperature Infrared/Convection 225°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T⊾ to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	225°C Maximum
Target Peak Temperature (T _P Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t _p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.